

WHAT IS CLAIMED IS:

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1.A method of fabricating an organic electroluminescence panel package comprising the steps of:

5 providing a printed circuit board arranged with a plurality of solder pads;

forming a plurality of bumps on the solder pads;

providing at least an organic electroluminescence (OEL) panel arranged on the printed circuit board, wherein the organic electroluminescence (OEL) panel comprises a plurality of poly solder interconnections; and

10 performing a re-flow process to electrically connect the poly solder interconnections and the bumps.

2.The packaging fabrication of claim 1, wherein the bumps are formed on the solder pad by means of a wire bonding machine.

3.The packaging fabrication of claim 1, wherein the poly solder interconnections are formed by screen printing or dispensing.

4.The packaging fabrication of claim 1, wherein the poly solder interconnections include silver paste.

5.The packaging fabrication of claim 1, wherein the poly solder interconnections include low re-flow temperature material.

6. The packaging fabrication of claim 1, wherein the poly solder interconnections are arranged in area array.

5 7. A method of fabricating organic electroluminescence panel comprising the steps of

 providing a substrate;

 forming a plurality of first electrodes on the substrate, wherein the first electrode includes a driving region and at least an interconnection region and the

10 interconnection region is protruded from the driving region;

 forming at least a patterned organic electroluminescence panel layer on the substrate, wherein the patterned organic light-emitting layer exposes the interconnection;

 forming a plurality of second electrodes on the organic light-emitting layer;

15 and

 forming a plurality of poly solder interconnections on the interconnection region and on the second electrodes.

 8. The method of claim 7, wherein each of the driving regions of the first

20 electrodes is a stripe.

 9. The method of claim 7, wherein each of the driving regions of the second electrodes is a stripe.

10. The method of claim 7, wherein the extension direction of the first electrodes
is perpendicular to
the extension direction of the second electrodes.

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11. The method of claim 7, wherein the material for the first electrodes includes
Indium Tin Oxide (ITO), Indium Zinc Oxide (IZO), or Aluminium Zinc Oxide (AZO).

12. The method of claim 7, wherein the material for the second electrodes include
10 metal.

13. The method of claim 7, wherein the poly solder interconnections include
silver paste.

14. The method of claim 7, wherein the poly solder interconnections are formed
15 by screen printing or paste.

15. The method of claim 7, wherein the formation of the patterned organic light-
emitting layer comprises the steps of:

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forming an organic light-emitting layer; and
defining the organic light-emitting layer to form a plurality of openings thereon,
wherein the openings expose the interconnection regions.

16. The method of claim 7, wherein the formation of the patterned organic light-emitting layer comprises the steps of:

forming an organic light-emitting layer; and

defining the organic light-emitting layer to form a plurality of stripes thereon,

5 wherein the openings expose the interconnection regions.

17. The method of claim 7, wherein further comprising the step of forming a hole injection layer between the first electrodes and the organic light-emitting layer after the formation of the first electrodes but before the formation of the light-emitting layer.

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18. The method of claim 17, further comprising the step of forming a hole transmitting layer between the hole injection layer and the organic light-emitting layer after the formation of the electron injection layer but before the formation of the light emitting layer.

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19. The method of claim 7, further comprising the step of forming an electron transmitting layer

between the organic light-emitting layer and the second electrode after the formation of the organic light-emitting layer but before the formation of the second electrodes.

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20. The method of claim 19, further comprising the step of forming an electron injection layer

between the electron transmitting layer and the second electrodes after the formation of the electron transmitting layer but before the formation of the cathode.

5 21. The method of claim 7, wherein the poly solder interconnections include low re-flow temperature materials.

22. The method of claim 7, wherein the poly solder interconnections are in area array.

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